

ABSTRACT OF THE DISCLOSURE

A package substrate manufactured by electrolytically plating Au in a semi-additive manner without using any plating lead line on wire bonding pads and solder ball pads, and a method for manufacturing the package substrate. The method includes the steps of forming a first copper plated layer on a base substrate having through holes and inner surfaces of the through holes, coating a first resist over the first copper plated layer, partially removing the first resist, thereby exposing portions of the first copper plated layer respectively corresponding to regions where circuit patterns are to be plated, forming a second copper plated layer on the exposed portions of the first copper plated layer, stripping the first resist, coating a second resist over the resultant structure, and removing the second resist from regions where wire bonding pads and solder ball pads are to be formed, removing exposed portions of the first copper plated layer, forming the wire bonding pads and the solder ball pads, removing the second resist, removing exposed portions of the first copper plated layer, and coating a solder resist over all surfaces of the resultant structure, and removing portions of the solder resist respectively covering the wire bonding pads and the solder ball pads.